

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	19	((print\$2 adj circuit adj board) PCB) same (conduct\$5 same (ground\$5 shield\$5))) and 349/149-152.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:43
L2	60	((print\$2 adj circuit adj board) PCB) same (conduct\$5 same (ground\$5 shield\$5))) and "349"/\$.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:44
L3	50	2 and @ad<"20040303"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:44
L4	112	((flexible adj flat adj cable) FFC) same cover\$5 same (passivation dielectric insulating insulator)) and @ad<"20040303"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:46
L5	0	4 and 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:47
L6	0	((frame housing chassis) same ((print\$2 adj circuit adj board) PCB) same ((flexible adj flat adj cable) FFC) same (shield\$5 ground\$5) same electric same conduct\$5 same (liquid adj crystal)) and @ad<"20040303"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:49
L7	7	((frame housing chassis) and ((print\$2 adj circuit adj board) PCB) and ((flexible adj flat adj cable) FFC) and (shield\$5 ground\$5) and conduct\$5 and (liquid adj crystal) and (passivation dielectric)) and @ad<"20040303"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:51

## EAST Search History

L8	23	((frame housing chassis) and ((print\$2 adj circuit adj board) PCB) and ((flexible adj flat adj cable) FFC) and (shield\$5 ground\$5) and conduct\$5 and (passivation dielectric)) and @ad<"20040303"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:51
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## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L9	1	((frame housing chassis) and ((print\$2 adj circuit adj board) PCB) and ((flexible adj flat adj cable) FFC) and (shield\$5 ground\$5) and conduct\$5 and (passivation dielectric)).CLM.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/11/11 13:52
L10	1	((frame housing chassis) and ((print\$2 adj circuit adj board) PCB) and ((flexible adj flat adj cable) FFC) and (shield\$5 ground\$5) and conduct\$5 and (passivation dielectric)).CLM.	US-PGPUB	OR	ON	2006/11/11 13:52
L11	71	((frame housing chassis) and ((print\$2 adj circuit adj board) PCB) and (shield\$5 ground\$5) and conduct\$5 and (passivation dielectric)).CLM.	US-PGPUB	OR	ON	2006/11/11 13:52
L12	46	11 and @ad<"20040303"	US-PGPUB	OR	ON	2006/11/11 13:53